



## International Conference on IC Design & Technology

Otranto, Italy, June 4<sup>th</sup>– 6<sup>th</sup>, 2018

<http://www.ICICDT.org>



Integrated circuit (IC) engineering roles have traditionally been separated along the boundary between design and technology. As IC products advance toward higher performance with better energy efficiency and ultra-low power consumption for leading applications such as internet of thing (IoT), artificial intelligence, and autonomous cars, cost control and time to market continue to be mandated. The present and future IC engineers will require a deeper understanding of the interdependencies between design and technology options to continue to expand the product optimization window. ICICDT is an ideal forum for engineers, researchers, graduate students and professors, to cross the design-technology boundary through interactions with design, technology, and process experts to develop the skills for future IC research and development. This year we are soliciting papers in the field of Quantum computing and hope that this will be a great opportunity to support the advancement in this exciting field. We extend our invitation to you to submit papers, present and discuss your works at the 2018 ICICDT conference.

### 2018 ICICDT Venue:

The venue of 2018 International Conference on IC Design and Technology (ICICDT) will be in the historical triangular hall of the Castle of Otranto (1067 D.C.).



### Contributed papers are solicited in the following subject areas:

- Advanced materials and processing technologies
- Advanced transistor and interconnect structures
- Interposer/Three-Dimensional (2.5D/3D) integration
- Variation-tolerant designs
- Process and design techniques for soft errors, plasma-induced damage, and reliability
- Advanced and emerging memory devices and circuits
- RF, analog, mixed signal, and I/O circuits for future technology generations
- Simulation and modeling of advanced processes, devices, and circuits
- EDA and design optimizations across system, circuit, and/or device levels for high performance, energy efficiency, yield, and/or reliability
- Design for manufacturing, yield, and test
- System-on-Chip (SoC) and system-in-package (SiP) design integration
- Power semiconductor technologies and circuits
- Emerging technologies, circuits and Applications (Internet of Thing, Autonomous cars, Machine Learning, Artificial Intelligence)
- Quantum computing

**Paper Submission Deadline: February, 9<sup>th</sup>, 2018**

### Conference Sponsors



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